

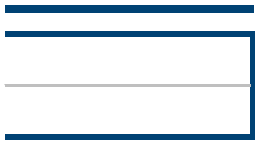
Grade	SFI-553
Product	Random PP

General Information	
Key Features	PANPELEN SFI-553 is a controlled medium modulus random copolymer designed for water quenched offers an excellent clarity and gloss, a very low ha range and a low seal-initiation temperature. It is c packaging applications, as heat seal layer film. It c antiblock additives.
Applications	Cloth packaging, food packaging

Item	Measuring Method	Unit
Physical		
Melt Flow Index	ASTM D1238	g/10min
Density	ASTM D792	g/cm ³
Mechanical		
Tensile Stress (Yield)	ASTM D638	kgf/cm ²
Tensile Strain (Break)	ASTM D638	%
Flexural Modulus	ASTM D790	kgf/cm ²
Impact		
Notched Izod Impact Strength (23°C)	ASTM D256	kgf·cm/cm
Rockwell Hardness	ASTM D785	R
Thermal		
Melting Point	ASTM D3418	°C
Heat Deflection Temperature (4.6kgf/cm ²)	ASTM D648	°C

1. Physical Properties : these are not to be construed as specifications

* The last update date : 2021/10/01



ed polypropylene
film technology. It
ze, a wide hot tack
designed for quality
contains slip and



Value
7.0
0.9
230
>500
7,800
10
82
135
72